## Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

## Listing of Claims:

- 5 1 (currently amended): A nitride based light emitting diode (LED) comprising: a substrate:
  - a first conductivity type contact layer formed over the substrate, the first conductivity type contact layer being made of  $Al_{xl}In_{yl}Ga_{l-(xl+yl)}N$  ( $0 \le x1 \le 1$ ;  $0 \le y1 \le 1$ ; and  $0 \le x1+y1 \le 1$ );
- a light emitting layer formed over the first conductivity type nitride based contact layer;
  - a second conductivity type contact layer formed over the light emitting layer, the second conductivity type contact layer being made of  $Al_{x2}In_{y2}Ga_{1-(x2+y2)}N$  ( $0 \le x2 \le 1$ ;  $0 \le y2 \le 1$ ; and  $0 \le x2+y2 \le 1$ );
- 15 a light emitting stacked structure formed over the substrate;
  - a nitride based dual dopant contact layer formed over the second conductivity type contact layer light-omitting stacked structure, the nitride based dual dopant contact layer comprising at least a p-type impurity dopant and an [[a]] n-type impurity wherein dopant, and a material of the p-type dopant being different from a material of the n-type dopant a concentration of the n-type impurity being higher than a concentration of the p-type impurity; and
  - a transparent conductive oxide layer formed over the nitride based dual dopant contact layer.
- 25 2 (previously presented): The LED of claim 1, wherein the nitride based dual dopant contact layer is made of Al<sub>a</sub>In<sub>b</sub>Ga<sub>1-(n+b)</sub>N (0≤a≤1; 0≤b≤1; and 0≤a+b≤1), the transparent conductive oxide layer is made of indium-tin oxide (ITO), cadmium-tin oxide, antimony-tin oxide (ATO), zinc oxide (ZnO), or zinc-tin oxide.

- 3 (currently amended): The LED of claim 1, wherein the nitride based dual dopant contact layer is formed by adding the p-type dopants impurity and the n-type dopants impurity together through an epitaxy growth.
- 4 (previously presented): The LED of claim 1, wherein the nitride based dual dopant contact layer is formed by: providing a second conductive type contact layer on the light emitting stacked structure; then providing a first conductive type contact layer on the second conductive type contact layer; and then cooling the LED through a cooling rate less than 40°C/min.

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- 5-6 (cancelled).
- 7 (currently amended): The LED of elaim-5 claim 1, wherein the multiple quantum well light emitting layer has r InGaN quantum wells and (r+1) InGaN barriers, each InGaN quantum well is sandwiched in between two InGaN barriers, each InGaN quantum well is fabricated by In₂Ga<sub>1-2</sub>N, and each InGaN barrier is made of In₁Ga<sub>1-1</sub>N, r≥ 1, and 0≤f<e≤1.</p>
- 8 (currently amended): The LED of elaim-5 claim 1 further comprising a first conductivity type cladding layer interposed between the first conductivity type contact layer and the multiple quantum well light emitting layer, and the first conductivity type cladding layer is made of Al<sub>x</sub>Ga<sub>1-x</sub>N, and 0≤x≤1.
- 9 (currently amended): The LED of elaim-5 claim 1 further comprising a second conductivity type cladding layer interposed between the second conductivity type contact layer and the multiple quantum well light emitting layer, and the second conductivity type cladding layer is made of Al₂Ga<sub>1.2</sub>N, and 0≤z≤1.
  - 10-18 (cancelled).

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19 (currently amended): The LED of claim I wherein the nitride based dual dopant

contact layer is made of  $Al_aIn_bGa_{1-(a+b)}N$  ( $0 \le a \le 1$ ;  $0 \le b \le 1$ ; and  $0 \le a+b \le 1$ ); the n-type departs are impurity is selected from the group consisting made of Si, Ge, Sn, Te, O, S, or and C; and the p-type departs are impurity is selected from the group consisting made of Mg, Zn, Be, or and Ca.

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- 20 (currently amended): A nitride based light emitting diode (LED) comprising: a substrate;
- a light emitting stacked structure formed over the substrate;
- a nitride based dual dopant contact layer formed over the light emitting stacked

  10 structure, the nitride based dual dopant contact layer being made of

  AlaInbGat (a+b)N (0≤a≤1; 0≤b≤1; and 0≤a+b≤1) and comprising at least a

  p-type dopant and an n-type dopant, a material of the p-type dopant being different from a material of the n-type dopant
  - a nitride based dual dopant contact layer formed over the light emitting stacked structure, the nitride based dual dopant contact layer comprising a p-type impurity and an n-type impurity, wherein the dual dopant contact layer is essentially not p-type; and
    - a transparent conductive oxide layer formed over the nitride based dual dopant contact layer.

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- 21 (cancelled).
- 22 (new): The LED of claim 20, wherein the nitride based dual dopant contact layer is made of Al<sub>a</sub>In<sub>b</sub>Ga<sub>1-(a+b)</sub>N (0≤a≤1; 0≤b≤1; and 0≤a+b≤1), the transparent conductive oxide layer is made of indium-tin oxide (ITO), cadmium-tin oxide, antimony-tin oxide (ATO), zinc oxide (ZnO), or zinc-tin oxide.
- 23 (new): The LED of claim 20, wherein the nitride based dual dopant contact layer is formed by adding the p-type impurity and the n-type impurity together through an epitaxy growth.

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- 24 (new): The LED of claim 20, wherein the light emitting stacked structure comprises a multiple quantum well, the multiple quantum well has r lnGaN quantum wells and (r+1) InGaN barriers, each InGaN quantum well is sandwiched in between two InGaN barriers, each InGaN quantum well is fabricated by In<sub>c</sub>Ga<sub>1-c</sub>N, and each InGaN barrier is made of ln<sub>r</sub>Ga<sub>1-t</sub>N, r≥1, and 0≤f<e≤1.
- 25 (new): The LED of claim 24 further comprising a first conductivity type cladding layer interposed between the first conductivity type contact layer and the multiple quantum well light emitting layer and the first conductivity type cladding layer is made of Al<sub>x</sub>Ga<sub>1-x</sub>N, and 0≤x≤1.
- 26 (new): The LED of claim 24 further comprising a second conductivity type cladding layer interposed between the second conductivity type contact layer and the multiple quantum well light emitting layer and the second conductivity type cladding layer is made of  $Al_zGa_{1-z}N$ , and  $0 \le z \le 1$ .
- 27 (new): The LED of claim 20 wherein the nitride based dual dopant contact layer is made of Al<sub>a</sub>In<sub>b</sub>Ga<sub>1-(a+b)</sub>N (0 ≤ a ≤ 1; 0 ≤ b ≤ 1; and 0 ≤ a+b ≤ 1); the n-type impurity are made of Si, Ge, Sn, Te, O, S, or C; and the p-type impurity are made of Mg, Zn, Be, or Ca.
- 28 (new): The LED of claim 20 wherein the dual dopant contact layer has a thickness less than 60 angstroms.
- 29 (new) The LED of claim 1 wherein the dual dopant contact layer has a thickness less than 60 angstroms.
- 30 (new): A nitride based light emitting diode (LED) comprising:
- 30 a substrate;
  - a light emitting stacked structure formed over the substrate;

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- a nitride based dual dopant contact layer formed over the light emitting stacked structure, the nitride based dual dopant contact layer comprising a p-type impurity and an n-type impurity wherein the dual dopant contact layer is essentially not a highly conductive layer; and
- 5 a transparent conductive oxide layer formed over the nitride based dual dopant contact layer.
  - 31 (new): The LED of claim 30, wherein the nitride based dual dopant contact layer is made of Al<sub>a</sub>In<sub>b</sub>Oa<sub>1·(a+b)</sub>N (0≤a≤1; 0≤b≤1; and 0≤a+b≤1), the transparent conductive oxide layer is made of indium-tin oxide (ITO), cadmium-tin oxide, antimony-tin oxide (ATO), zinc oxide (ZnO), or zinc-tin oxide.
  - 32 (new): The LED of claim 30, wherein the nitride based dual dopant contact layer is formed by adding the p-type impurity and the n-type dopants together through an epitaxy growth.
  - 33 (new): The LED of claim 30, wherein the light emitting stacked structure comprising a multiple quantum well, the multiple quantum well has r InGaN quantum wells and (r+1) InGaN barriers, each InGaN quantum well is sandwiched in between two InGaN barriers, each InGaN quantum well is fabricated by In<sub>e</sub>Ga<sub>1-e</sub>N, and each InGaN barrier is made of In<sub>1</sub>Ga<sub>1-f</sub>N, r≥1, and 0≤f<e≤1.
- 34 (new): The LED of claim 33 further comprising a first conductivity type cladding layer interposed between the first conductivity type contact layer and the multiple quantum well light emitting layer and the first conductivity type cladding layer is made of Al<sub>x</sub>Ga<sub>1-x</sub>N, and 0≤x≤1.
- 35 (new): The LED of claim 33 further comprising a second conductivity type cladding layer interposed between the second conductivity type contact layer and the multiple quantum well light emitting layer and the second conductivity

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To: USPTO

type cladding layer is made of  $Al_zGa_{1-z}N$ , and  $0 \le z \le 1$ .

- 36 (new): The LED of claim 30 wherein the nitride based dual dopant contact layer is made of  $Al_aIn_bGa_{1-(a+b)}N$  ( $0 \le a \le 1$ ;  $0 \le b \le 1$ ; and  $0 \le a+b \le 1$ ); the n-type impurity are made of Si, Ge, Sn, Te, O, S, or C; and the p-type impurity are made of Mg, Zn, Be, or Ca.
- 37 (new): The LED of claim 30 wherein the dual dopant contact layer has a thickness less than 60 angstroms.
- 38 (new): The LED of claim 30 wherein the dual dopant contact layer has a p-type carrier concentration lower than 5x10<sup>18</sup> cm<sup>-3</sup>.